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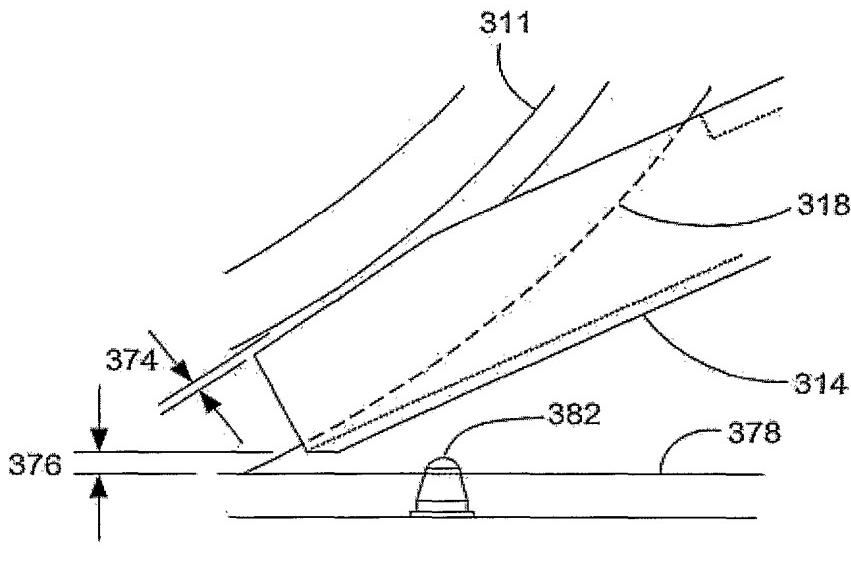
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(54) Title: NOZZLE ASSEMBLY FOR A SAW FOR SEMICONDUCTORS



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(57) Abstract: A nozzle assembly (314) for directing flow of fluid across one or more semiconductor device cutting blades (318), comprising: one or more nozzles configured to protrude toward a cutting blade for cutting a semiconductor device; and a channel formed in each of the nozzles, the channel being configured to at least partially surround the cutting blade, so as to simultaneously direct flow of a fluid onto the cutting edge of the cutting blade and onto the sides of the cutting blade.



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